

**INDEX BY DEVICE TYPE OF REGISTERED  
MICROELECTRONIC STANDARD OUTLINES (MS)**

FAMILY	REGISTRATION NO.
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**BALL GRID ARRAY**

Rectangular Plastic BGA, 1.27 mm, 1.0 mm Pitch	MS-028
Plastic Square BGA 1.0mm, 1.27mm 1.50 mm Pitch	MS-034

**CHIP CARRIERS (LCC & PLCC)**

LEADLESS Type A .050" Centers	MS-002
LEADLESS Type B .050" Centers	MS-003
LEADLESS Type C .050" Centers	MS-004
LEADLESS Type D .050" Centers	MS-005
LEADED Type A .050" Centers	MS-006
LEADED Type A .050" Centers	MS-007
LEADED Type B .050" Centers	MS-008
LEADLESS Chip Carrier .040" Centers	MS-009
LEADLESS Single Layer .040" Centers	MS-014
Plastic Chip Carrier .050" Spacing	MS-016
Plastic Chip Carrier .050" Spacing	MS-018

**DUAL-IN-LINE FAMILY (DIP)**

.300" Row Spacing	MS-001
.400" Row Spacing	MS-011
.400" Row Spacing Plastic	MS-010
.300/.400/.600/.900 SIDE BRAZED	MS-015
.300 (.070" pitch)	MS-019
.600 (.070" pitch)	MS-020
.750 (.070" pitch)	MS-021
.300" Row Spacing Ceramic	MS-030
.400" Row Spacing Ceramic	MS-031
.600" Row Spacing Ceramic	MS-032

**PIN GRID ARRAY (PGA)**

Ceramic PGA .100" Pitch Cavity Down	MS-017
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**QUAD FLATPACK (QFP)**

Plastic 1.0 & 1.4 mm thick, 2mm footprint	MS-026
Metric Plastic 1.0, 0.8, 0.65 mm pitch	MS-022

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**QUAD FLATPACK (QFP) (cont'd)**

Fine Pitch Plastic QFP 2.6 mm footprint MS-029

**SMALL OUTLINE (SO & TSOP)**

.150" Body Width SO MS-012

.300" Body Width SO MS-013

.300" Plastic SOJ MS-023

.400" SOJ MS-027

10.16 mm Body TSOPII MS-024

7.62 mm Body TSOPII MS-025